

• Product Summary

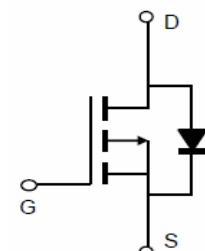
Part #	V _{DS}	R _{DS(on).typ} (@V _{GS} =10V)	R _{DS(on).typ} (@V _{GS} =4.5V)	I _D
EFM700P06D	-60V	70mΩ	85mΩ	-15A

• Description

- The EFM700P06D is the high cell density trenched
- P-ch MOSFETs which provide excellent
- RDSON and gate charge for most of the
- synchronous buck converter applications.
- The EFM700P06D meet the RoHS and Green
- Product requirement, 100 % EAS guaranteed
- with full function reliability approved.

• Application

- Super Low Gate Charge 100% EAS Guaranteed
- Green Device Available Excellent CdV/dt effect decline
- Advanced high cell density Trench technology



P-Channel MOSFET



TO-252-2L

• Ordering Information:

Part NO.	EFM700P06D
Marking	700P06D ****
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

• Absolute Maximum Ratings (T_C=25°C)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-60	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	-15	A
Drain Current-Pulsed ^(Note 1)	I _{DM}	-26	A
Maximum Power Dissipation	P _D	31.3	W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 To 150	°C

• Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	R _{θJA}	62	°C/W
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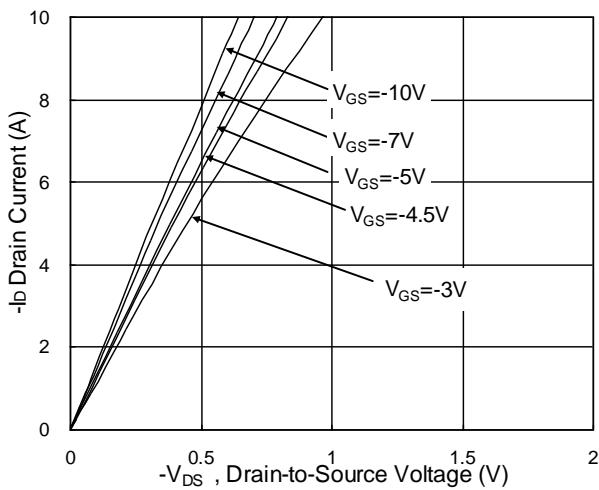
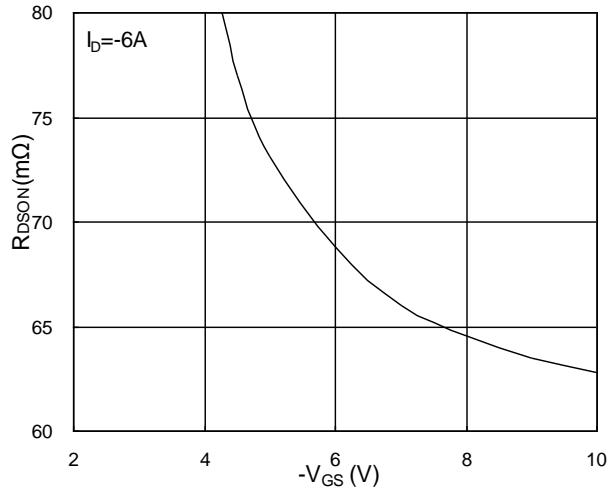
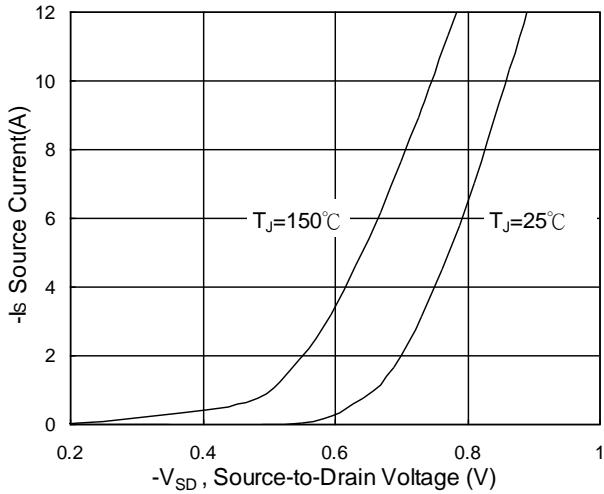
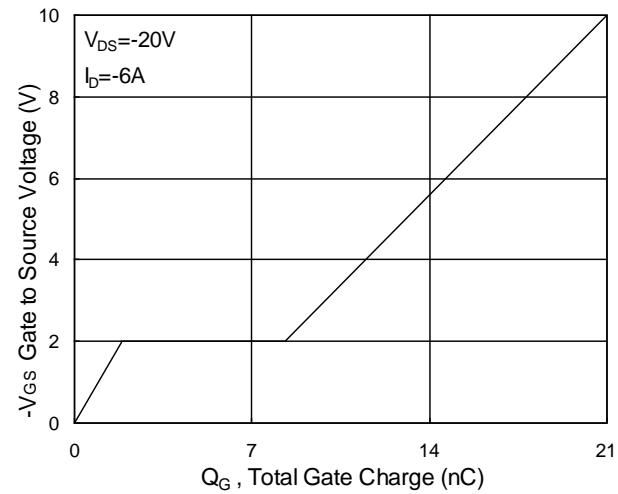
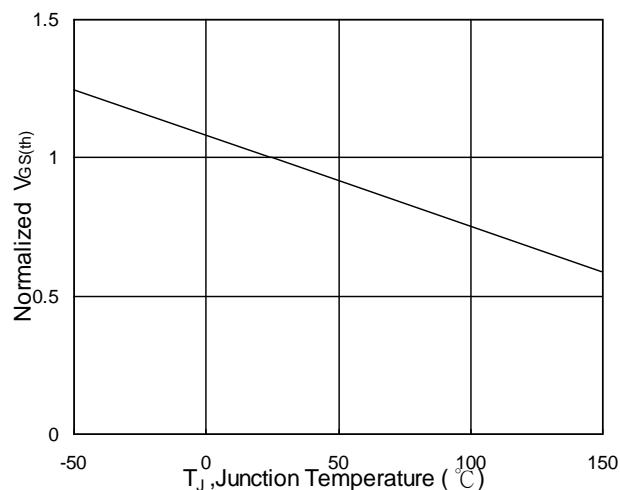
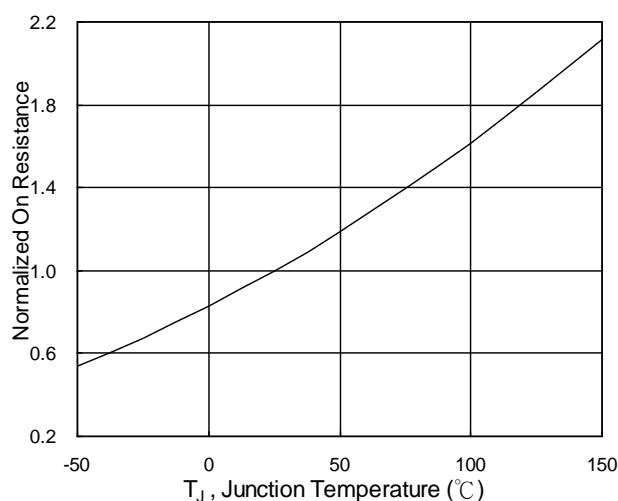
• Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

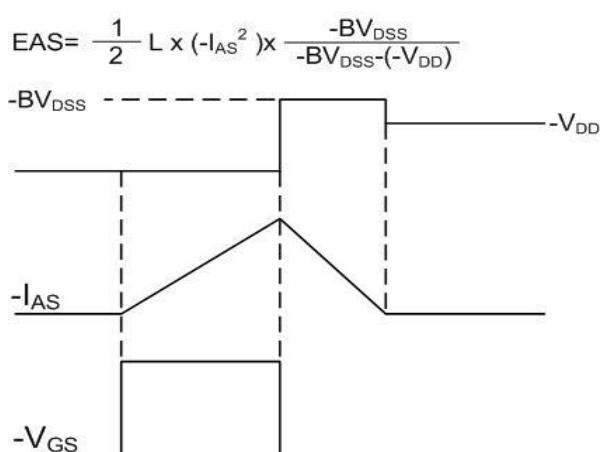
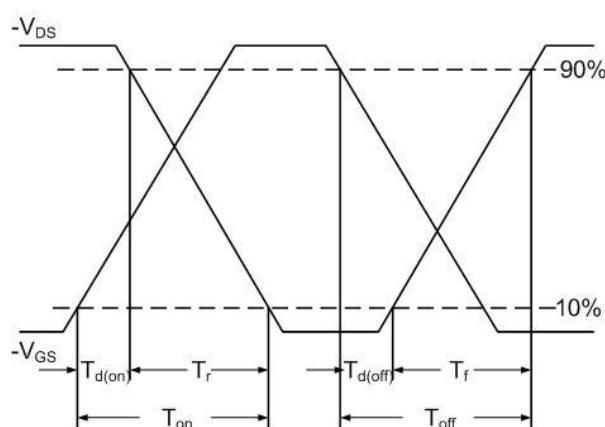
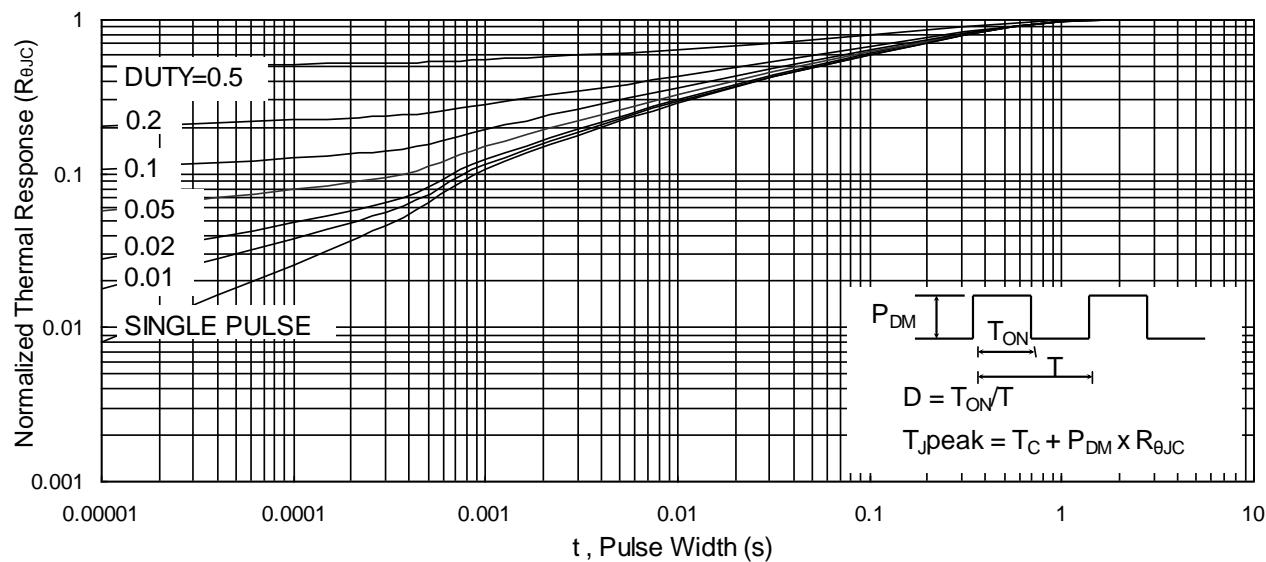
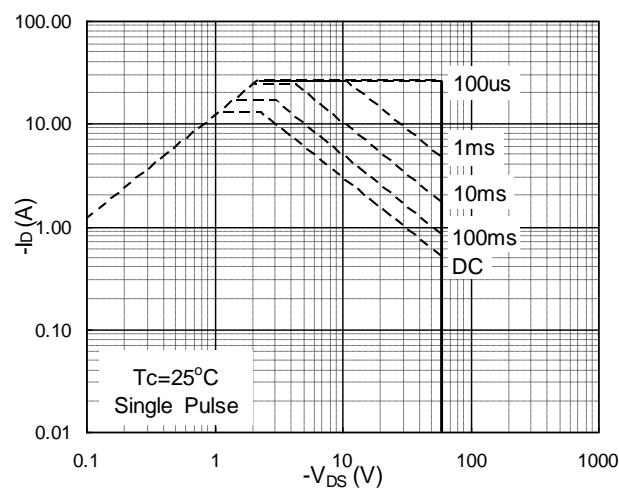
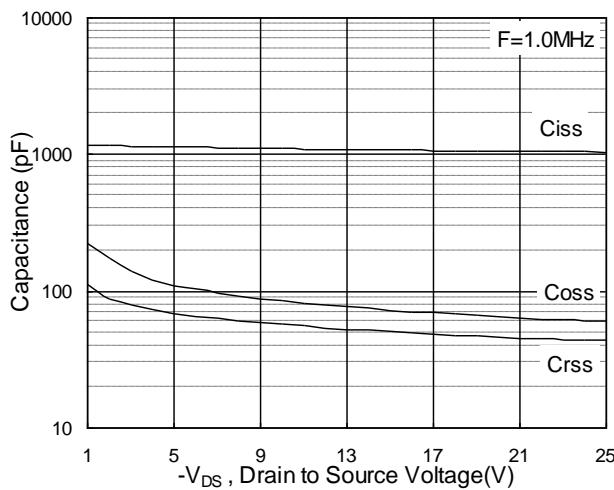
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V} I_{\text{D}}=250\mu\text{A}$	-60	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-48\text{V} V_{\text{GS}}=0\text{V}$	--	--	-1	nA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V} V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
On Characteristics <small>(Note 3)</small>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}} I_{\text{D}}=250\mu\text{A}$	-1.0	--	-2.5	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-10\text{V} I_{\text{D}}=-10\text{A}$	--	70	90	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V} I_{\text{D}}=-5\text{A}$	--	85	115	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=-5\text{V} I_{\text{D}}=-4\text{A}$	--	8.7	--	S
Gate Resistance	R_g	$F=1.0\text{MHz}$	--	15	--	Ω
Dynamic Characteristics <small>(Note 4)</small>						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-15\text{V} V_{\text{GS}}=0\text{V}$ $F=1.0\text{MHz}$	--	1080	--	PF
Output Capacitance	C_{oss}		--	73	--	PF
Reverse Transfer Capacitance	C_{rss}		--	50	--	PF
Switching Characteristics <small>(Note 4)</small>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=-15\text{V} I_{\text{D}}=1\text{A}$ $V_{\text{GS}}=-10\text{V} R_{\text{G}}=3.3\Omega$	--	8.8	--	nS
Turn-on Rise Time	t_r		--	19.6	--	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		--	47.2	--	nS
Turn-Off Fall Time	t_f		--	9.6	--	nS
Total Gate Charge	Q_g	$V_{\text{DS}}=-12\text{V} I_{\text{D}}=-6\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	--	11.8	--	nC
Gate-Source Charge	Q_{gs}		--	1.9	--	nC
Gate-Drain Charge	Q_{gd}		--	6.5	--	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <small>(Note 3)</small>	V_{SD}	$V_{\text{GS}}=0\text{V} I_{\text{S}}=-1\text{A}$	--	--	-1	V
Diode Forward Current <small>(Note 2)</small>	I_{S}		--	--	-15	A

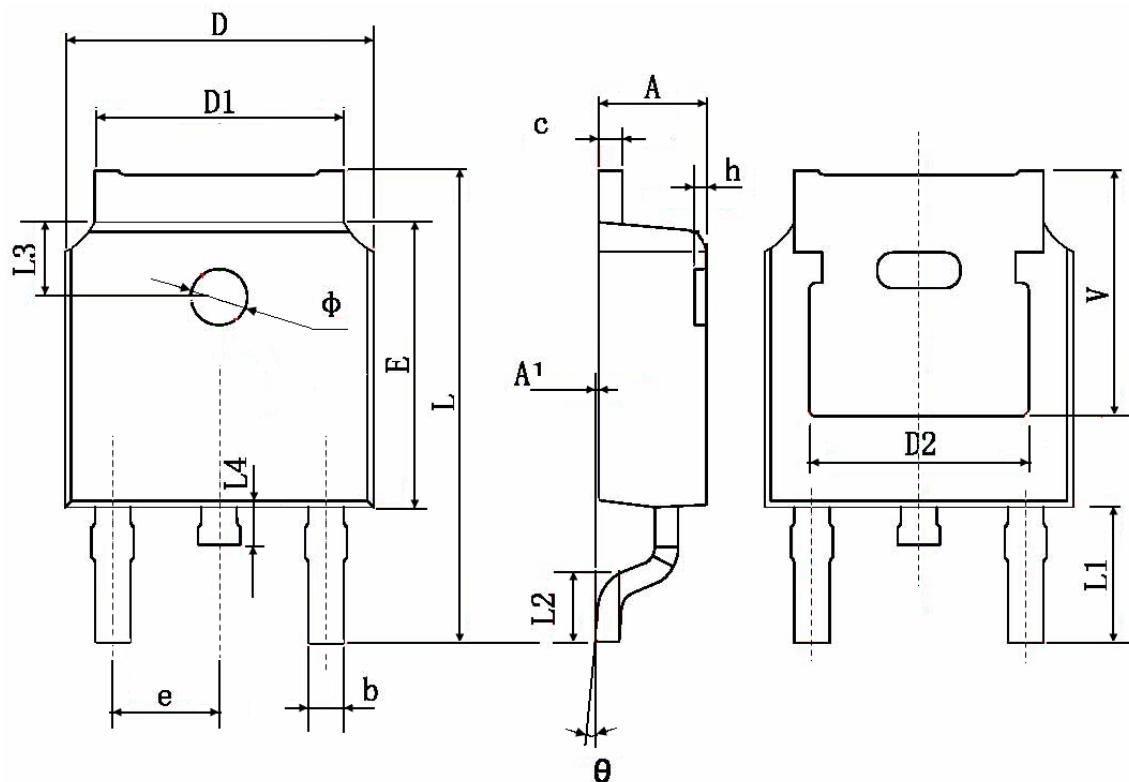
Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=-25\text{V}, V_{\text{GS}}=-10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=-24.4\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.

• Typical Characteristics


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance v.s Gate-Source

Fig.3 Forward Characteristics of Reverse

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ v.s T_J

Fig.6 Normalized $R_{DS(on)}$ v.s T_J



TO-252 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.83 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	